

# Mechanism of dissolution of MgO crystals in acids

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A simple model of dissolution of MgO crystals in acids involving chemical reactions and adsorption process on the crystal surface is used to derive expressions connecting rates of surface dissolution and selective etching with concentration, temperature and nature of an acid and with surface orientation. The experimental data of the dependence of etch rates of MgO on various etching parameters are then compared with the theory. The effect of acid viscosity and concentration are also briefly analysed and compared with the experimental observations. It is argued that the experimental results can be understood on the basis of the proposed mechanism if adsorption of the reactants and the complexes formed during dissolution on a perfect surface and at dislocation sites is taken into consideration. It is concluded that the adsorption processes play an important role in the formation of good, contrasting dislocation etch pits.

## 1. Introduction

The dissolution rate of MgO crystals depends on the nature, temperature and concentration of an acid and on the surface orientation [1-4]. The values of the activation energy and the pre-exponential factor of the dissolution process are frequently found to be dependent on the nature and concentration of an acid [1-3]. The activation energy remains constant while the pre-exponential factor of dissolution changes markedly from one surface to another [4]. Strong (HNO<sub>3</sub>, HCl and H<sub>2</sub>SO<sub>4</sub>) and weak (CH<sub>3</sub>COOH, C<sub>2</sub>H<sub>5</sub>COOH and C<sub>6</sub>H<sub>8</sub>O<sub>7</sub>) acids produce etch pits at fresh and old dislocations, but only dilute solutions of moderately weak acids (H<sub>3</sub>PO<sub>4</sub> and HCOOH) form etch pits at old dislocations [1-4].

According to the theory of two-dimensional dissolution [5], the dissolution rate is given by

$$v_s = d\nu_s \exp[-\Delta G_s^*/kT] \quad (1)$$

where  $d$  is the depth of a unit pit,  $\nu_s$  the frequency factor of the order of the Debye frequency and  $\Delta G_s^*$  the free energy change associated with the formation of a unit pit in a perfect surface of the crystal. Taking the depth of the unit pit as  $a$ ,  $1.3a$  and  $1.15a$  (where  $a = 4.2 \times 10^{-8}$  cm) on

{100}, {110} and {111} faces,  $\nu_s = 10^{13} \text{ sec}^{-1}$ , and multiplying by the product of the density of MgO and (60 × 60), we have the values of the pre-exponential factor of the surface dissolution as  $5.8 \times 10^9 \text{ g cm}^{-2} \text{ h}^{-1}$ ,  $7.3 \times 10^9 \text{ g cm}^{-2} \text{ h}^{-1}$  and  $6.7 \times 10^9 \text{ g cm}^{-2} \text{ h}^{-1}$  for {100}, {110} and {111} faces of MgO, respectively.

The free energy change  $\Delta G_s^* = \pi\gamma' dr_s^*$  [6], where  $\gamma'$  is the specific free energy of a molecule going from the solid to the solution and  $r_s^*$  the radius of the critical nucleus. Taking the typical values of  $r_s^* = d/2$  and  $\gamma' = \gamma/2$  as in the case of LiF [6], we have

$$\Delta G_s^* = \pi\gamma d^2/4. \quad (2)$$

Here  $\gamma$  is the specific surface free energy of the crystal in vacuum. Substituting the reported values [7] of  $\gamma$ , one obtains a value for  $\Delta G_s^*$  of 1.0 and 3.8 eV for {100} and {110} faces of MgO, respectively.

The theory of two-dimensional nucleation therefore yields values of the pre-exponential factor and the activation energy which are very much higher than the experimental values [1-3]. The theory also does not give a satisfactory explanation for the concentration dependence of

the pre-exponential factor, or for the constancy of the activation energy for different planes.

Recently a treatment of the dissolution process from a consideration of chemical reactions has been advanced to explain the anisotropy of the dissolution of quartz [8]. Though this treatment explains several features of the etching of quartz, it neither gives an estimate of the activation energy nor considers adsorption processes taking place on the crystal surface during dissolution.

In this paper a theory of dissolution of MgO crystals in acids is formulated and the experimental data reported so far analysed.

## 2. Model for dissolution

The dissociation of monobasic acids, for example HCl, HNO<sub>3</sub>, HCOOH, CH<sub>3</sub>COOH, etc., into a hydrogen ion, H<sup>+</sup>, and an anion, An<sup>-</sup>, is complete in only one step which corresponds to only one value of the dissociation constant, *k<sub>c</sub>*. A polybasic acid, such as H<sub>2</sub>SO<sub>4</sub>, H<sub>3</sub>PO<sub>4</sub>, (COOH)<sub>2</sub>, etc., dissociates in steps and a different and lower dissociation constant corresponds to the detachment of each H<sup>+</sup> ion. Invariably the first step dissociation constant is far greater than the following steps dissociation constants [9]. Consequently a polybasic acid may be considered as HAn. If *n<sub>H</sub>*, *n<sub>An</sub>* and *n<sub>a</sub>* are the concentrations (number of molecules/ions cm<sup>-3</sup>) of H<sup>+</sup>, An<sup>-</sup> and HAn, respectively, and α is the degree of dissociation of HAn, then *n<sub>H</sub>* = *n<sub>An</sub>* = α*n<sub>a</sub>*.

We assume that dissolution of MgO on the crystal-etchant interface involves the following consecutive steps:

(1) Availability of H<sup>+</sup> and An<sup>-</sup> ions on the surface.

(2) Capture and migration of H<sup>+</sup> and An<sup>-</sup> ions on the surface.

(3) Formation of a complex.

(4) Adsorption of the complex onto the surface.

(5) Formation of an activated complex on the surface.

(6) Adsorption of the activated complex.

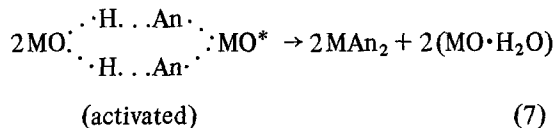
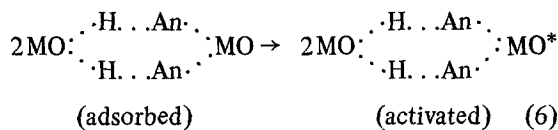
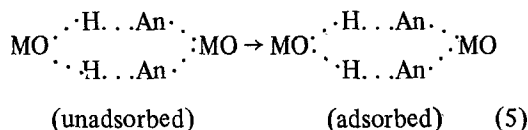
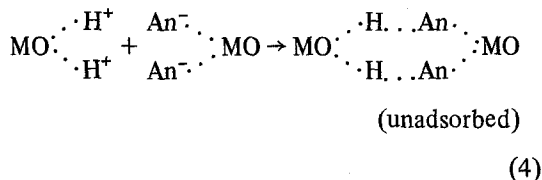
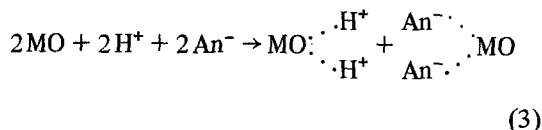
(7) Dissociation of the activated complex into reaction products.

(8) Adsorption of the reaction products on the surface.

(9) Transport of the reaction products into the etchant.

Steps 1 and 9 of the transport of the reacting and reacted species are determined by the diffusion kinetics, while the other steps may be regarded to

be limited by the reaction rate between the acid and the solid. Denoted Mg by M, the sequence of the etching process may be written as:



## 3. Rate of surface dissolution

Let *m<sub>H</sub>* and *m<sub>An</sub>* be the masses of H<sup>+</sup> and An<sup>-</sup> ions, respectively. Assuming that the velocity of the ions in dilute and concentrated solutions changes with *T* as in ideal gases, the numbers *n<sub>1</sub>* and *n<sub>2</sub>* of H<sup>+</sup> and An<sup>-</sup> ions striking the surface (cm<sup>-2</sup> sec<sup>-1</sup>) are

$$n_1 = n_{\text{H}} \left( \frac{3kT}{m_{\text{H}}} \right)^{1/2}$$

$$n_2 = n_{\text{An}} \left( \frac{3kT}{m_{\text{An}}} \right)^{1/2} \quad (8)$$

If the number of captured pairs of H<sup>+</sup> ions on the surface is *n<sub>3</sub>*, *E<sub>1</sub>* the energy required for the capture and migration of a pair of H<sup>+</sup> ions, then the change in the Helmholtz free energy is given by

$$F = E - TS$$

$$= n_3 E_1 - kT \ln \left[ \left( \frac{n_1!}{(n_1 - n_3)! n_3!} \right)^2 \right] \quad (9)$$

Using Stirling's formula  $\ln x! = x \ln x - x$ , the logarithmic term can be written as

$$\ln \left[ \frac{n_1!}{(n_1 - n_3)! n_3!} \right] \simeq n_1 \ln n_1 - (n_1 - n_3) \times \ln (n_1 - n_3) - n_3 \ln n_3.$$

When equilibrium is attained, the Helmholtz free energy is constant. Therefore

$$\left( \frac{\partial F}{\partial n_3} \right) = 0 = E_1 - 2kT [\ln (n_1 - n_3) - \ln n_3] = E_1 - 2kT \ln [(n_1 - n_3)/n_3].$$

Assuming  $n_1 \gg n_3$ , the above equation can be written as

$$n_3 = n_1 \exp [-E_1/(2kT)] \quad (10)$$

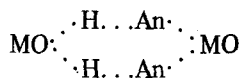
If  $\phi_1$  is a function which allows for the adsorption of a pair of  $H^+$  ions onto the surface and  $Z$  the number of free pairs of bonds on the surface, then the number  $n_3$  of the adsorbed pairs of  $H^+$  ions on the surface may be written as<sup>†</sup>

$$n_3 = \frac{\phi_1}{Z} n_1 \exp [-E_1/(2kT)] = \frac{\phi_1 n_H}{Z} (3kT/m_H)^{1/2} \exp [-E_1/(2kT)]. \quad (11)$$

Similarly if  $\phi_2$  is another adsorption function and  $E_2$  is the energy required for the capture and migration of a pair of  $An^-$  ions, then the number  $n_4$  of the captured pairs of  $An^-$  ions is

$$n_4 = \frac{\phi_2 n_{An}}{Z} (3kT/m_{An})^{1/2} \exp [-E_2/(2kT)]. \quad (12)$$

If  $E_3$  is the energy required for the formation of a complex



the change in the Helmholtz free energy produced by the formation of  $n_5$  complex molecules is

$$F = n_5 E_3 - kT \ln \frac{n_3!}{(n_3 - n_5)! n_5!} \cdot \frac{n_4!}{(n_4 - n_5)! n_5!}.$$

Substituting the solution of the factorial terms, obtained as before by using Stirling's formula, and differentiating with respect to  $n_5$ , at equilibrium from the above equation we get

<sup>†</sup>Corresponding to a high value of  $Z$ , adsorption of acid ions is expected to be more. But once equilibrium is attained the number of adsorbing ions decreases with increasing  $Z$  as a result of the repulsion of like charges accumulated on the surface. However, the dependence need not be simple as has been assumed.

$$\left( \frac{\partial F}{\partial n_5} \right) = 0 = E_3 - kT \ln \frac{(n_3 - n_5)(n_4 - n_5)}{n_5^2}.$$

For  $n_3 \gg n_5$  and  $n_4 \gg n_5$ , this equation may be rearranged in the form

$$n_5 = n_3^{1/2} n_4^{1/2} \exp [-E_3/(2kT)] = \frac{(\phi_1 \phi_2 n_H n_{An} 3kT)^{1/2}}{Z m_H^{1/4} m_{An}^{1/4}} \times \exp \left\{ - \left[ \frac{1}{4}(E_1 + E_2) + (E_3/2) \right] / kT \right\}. \quad (13)$$

If  $E_4$  is the energy of adsorption of a complex molecule on the surface, the number  $n_6$  of the adsorbed molecules on the surface is

$$n_6 = n_5 \exp [-E_4/(kT)] \quad (14)$$

If  $n_{Mg}$  is the density of  $Mg^{2+}$  and  $O^{2-}$  ions on a surface, the number density  $n_7$  of the adsorbed complex molecules on the surface is

$$n_7 = n_6 / n_{Mg} = \frac{(\phi_1 \phi_2 n_H n_{An} 3kT)^{1/2}}{Z n_{Mg} m_H^{1/4} m_{An}^{1/4}} \times \exp \left\{ - \left[ \frac{1}{4}(E_1 + E_2) + \frac{1}{2}E_3 + E_4 \right] / kT \right\}. \quad (15)$$

If  $E_5$  is the energy required for the formation of an activated complex, the number density  $n_8$  of the activated complex on the surface is

$$n_8 = n_7 \exp [-E_5/(2kT)] = \frac{(\phi_1 \phi_2 n_H n_{An} 3kT)^{1/2}}{Z n_{Mg} m_H^{1/4} m_{An}^{1/4}} \times \exp \left\{ - \left[ \frac{1}{4}(E_1 + E_2) + \frac{1}{2}E_3 + E_4 + \frac{1}{2}E_5 \right] / kT \right\}. \quad (16)$$

If  $\delta$  is the interval along the potential barrier over which the activated complex passes before dissociating with a frequency [9]

$$\nu = \frac{1}{\delta} \left( \frac{kT}{2\pi\mu} \right)^{1/2}$$

into reaction products, the number  $n_9$  of the activated complex molecules that can dissociate is

$$n_9 = n_8 \nu = \frac{n_8}{\delta} \left( \frac{kT}{2\pi\mu} \right)^{1/2}.$$

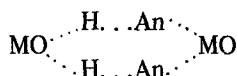
If  $E_6$  is the energy of dissociation of an activated complex molecule into products, the number  $n_{10}$  of the formation of a pair of  $\text{MAN}_2$  molecules is

$$n_{10} = n_9 \exp [-E_6/(2kT)] \\ = \frac{n_8}{\delta} \left( \frac{kT}{2\pi\mu} \right)^{1/2} \exp [-E_6/(2kT)]. \quad (17)$$

In the above equations  $\mu$  is the reduced mass of the activated complex, given by [9]

$$\mu = m_1/2 \quad (18)$$

where  $m_1$  is the mass of the complex



of which the activated complex is composed.

If  $d$  is the height of a dissolution step, the surface dissolution rate is

$$v = dn_{10} = \frac{dn_8}{\delta} \left( \frac{kT}{2\pi\mu} \right)^{1/2} \exp [-E_6/(2kT)] \\ = \frac{d(\phi_1\phi_2 n_{\text{H}} n_{\text{An}} 3kT)^{1/2}}{Z\delta n_{\text{Mg}} m_{\text{H}}^{1/4} m_{\text{An}}^{1/4}} \left( \frac{kT}{2\pi\mu} \right)^{1/2} \times \\ \exp \left\{ - \left[ \frac{1}{4}(E_1 + E_2) + \frac{1}{2}E_3 + E_4 \right. \right. \\ \left. \left. + \frac{1}{2}(E_5 + E_6) \right] / (kT) \right\} \quad (19)$$

Taking  $\phi_1\phi_2 = \phi^2$ ,  $n_a = N_A c$ , where  $N_A$  is the Avogadro number,  $c$  the acid concentration as a molarity and  $m_{\text{An}}/m_{\text{H}} = r_m$ , we may write the dissolution rate as

$$v = \frac{d\phi N_A \alpha c}{Z\delta n_{\text{Mg}} r_m^{1/4}} \left( \frac{3kT}{m_{\text{H}}} \frac{kT}{2\pi\mu} \right)^{1/2} \times \\ \exp \left\{ - \left[ \frac{1}{4}(E_1 + E_2) + \frac{1}{2}E_3 + E_4 \right. \right. \\ \left. \left. + \frac{1}{2}(E_5 + E_6) \right] / (kT) \right\}. \quad (20)$$

If  $\Delta E_s$  is the heat of adsorption of the activated complex on a perfect surface, the dissolution rate is

$$v_s = v \exp [\Delta E_s/(kT)] \\ = \frac{d\phi N_A \alpha c}{Z\delta n_{\text{Mg}} r_m^{1/4}} \left( \frac{3kT}{m_{\text{H}}} \frac{kT}{2\pi\mu} \right)^{1/2} \exp [\Delta E_s/(kT)] \\ \times \exp \left\{ - \left[ \frac{1}{4}(E_1 + E_2) + \frac{1}{2}E_3 + E_4 \right. \right. \\ \left. \left. + \frac{1}{2}(E_5 + E_6) \right] / (kT) \right\}. \quad (21)$$

Taking  $\delta = 10^{-9}$  cm,  $d = fa = f \times 4.2 \times 10^{-8}$  cm,  $N_A = 6 \times 10^{23}$ ,  $\mu^{1/2} = 10$  (Table I),  $r_m^{1/4} = 3$  (Table II),  $n_{\text{Mg}} = r_f n_{\text{Mg}}(100) = r_f \times 1.1322 \times 10^{15}$  cm $^{-2}$ ,  $\Delta E_s = 4$  kcal mol $^{-1}$  (equal to the heat of adsorption of a complex [10]), we obtain

$$v_s = \frac{28.4f\phi\alpha c}{Zr_f} \exp \left\{ - \left[ \frac{1}{4}(E_1 + E_2) + \frac{1}{2}E_3 + E_4 \right. \right. \\ \left. \left. + \frac{1}{2}(E_5 + E_6) \right] / (kT) \right\} \quad (22)$$

in cm sec $^{-1}$ . Here  $r_f$  is the ratio of the concentration of  $\text{Mg}^{2+}$  ions on a face to that on the {100} face, and  $f$  the ratio of the depth of a unit pit on a face under consideration to the depth of the pit on the {100} face. Multiplying Equation 22 by the density of MgO and (60 × 60), we have the dissolution rate, in g cm $^{-2}$  h $^{-1}$ , as

$$v_s = A_s \exp [-E_s/(kT)] \quad (23)$$

where

$$A_s = 3.66 \times 10^5 \frac{f\phi\alpha c}{Zr_f} \quad (24)$$

and

$$E_s = \left[ \frac{1}{4}(E_1 + E_2) + \frac{1}{2}E_3 + E_4 + \frac{1}{2}(E_5 + E_6) \right].$$

Since  $E_5 + E_6 = \Delta H^0$  the heat of formation of the reactants (i.e. the heat of the reaction) is given by

$$E_s = \left[ \frac{1}{4}(E_1 + E_2) + \frac{1}{2}E_3 + E_4 + \frac{1}{2}\Delta H^0 \right]. \quad (25)$$

TABLE I Reduced mass of some adsorbed complexes (mass of MgO = 40.3)

Complex	$m_1$	$\mu = m_1/2$	$\mu^{1/2}$
2MgO HCl	153.6	76.8	8.76
2MgO HNO <sub>3</sub>	206.6	103.3	10.16
2MgO HSO <sub>4</sub>	276.6	138.3	11.76
2MgO H <sub>2</sub> PO <sub>4</sub>	276.6	138.3	11.76
2MgO HCO <sub>2</sub>	172.6	86.3	9.29
2MgO CH <sub>3</sub> CO <sub>2</sub>	200.6	100.3	10.01
2MgO C <sub>2</sub> H <sub>5</sub> CO <sub>2</sub>	228.6	114.3	10.69
2MgO H(CO <sub>2</sub> ) <sub>2</sub>	260.6	130.3	11.41
2MgO HCO <sub>2</sub> (CHOH) <sub>2</sub> CO <sub>2</sub>	380.6	190.3	13.79
2MgO (CO <sub>2</sub> H) <sub>2</sub> CH <sub>2</sub> C(OH)CH <sub>2</sub> CO <sub>2</sub>	464.6	232.3	15.24

TABLE II Values of  $r_m^{1/4}$  of some ions

Ion	$r_m^{1/4}$	Ion	$r_m^{1/4}$
Cl <sup>-</sup>	2.45	CH <sub>3</sub> CO <sub>2</sub> <sup>-</sup>	2.75
NO <sub>3</sub> <sup>-</sup>	2.80	C <sub>2</sub> H <sub>5</sub> CO <sub>2</sub> <sup>-</sup>	2.90
HSO <sub>4</sub> <sup>-</sup>	3.12	H(CO <sub>2</sub> ) <sub>2</sub> <sup>-</sup>	3.08
H <sub>2</sub> PO <sub>4</sub> <sup>-</sup>	3.12	HCO <sub>2</sub> (CHOH) <sub>2</sub> CO <sub>2</sub> <sup>-</sup>	6.20
HCO <sub>2</sub> <sup>-</sup>	2.60	CO <sub>2</sub> HCH <sub>2</sub> C(OH)CH <sub>2</sub> CO <sub>2</sub> <sup>-</sup>	6.63

#### 4. Etch rates at dislocation

Lattice defects act as adsorption-active centres by virtue of their different adsorption potential [9]. If the energies involved at a dislocation site are denoted by  $E'$ , from Equation 22 the dissolution rate at a defect site can be given as

$$v_d = 3.66 \times 10^5 \frac{f\phi\alpha c}{Zr_f} \times \exp \left\{ - \left[ \frac{1}{4}(E'_1 + E'_2) + \frac{1}{2}E'_3 + E'_4 + \frac{1}{2}(E'_5 + E'_6) \right] / (kT) \right\}.$$

Since  $E_5 + E_6 = \Delta H^0 = E'_5 + E'_6 + \Delta H_d^0$  for a heterogeneous catalytic process [9],

$$v_d = 3.66 \times 10^5 \frac{f\phi\alpha c}{Zr_f} \exp \left[ \frac{\Delta H_d^0}{2kT} \right] \times \exp \left\{ - \left[ \frac{1}{4}(E'_1 + E'_2) + \frac{1}{2}E'_3 + E'_4 + \frac{1}{2}\Delta H^0 \right] / (kT) \right\}.$$

Taking a typical value of the heat of desorption,  $\Delta H_d^0$ , of the complex at a dislocation site equal to the heat,  $E_4$ , of adsorption of the complex, the above expression may be written as

$$v_d = A_d \exp \left[ -E_d / (kT) \right] \quad (26)$$

with

$$A_d = 2.0 \times 10^7 \frac{f\phi\alpha c}{Zr_f} \quad (27)$$

and

$$E_d = \left[ \frac{1}{4}(E'_1 + E'_2) + \frac{1}{2}E'_3 + E'_4 + \frac{1}{2}\Delta H^0 \right] \quad (28)$$

#### 5. Diffusion-controlled dissolution

When a crystal is placed in a reactant, a diffusion layer of thickness,  $\delta_f$ , develops at the solid-liquid interface. If  $v_1$  and  $v_2$  are the true and apparent dissolution rates on the surface,  $c_1$  and  $c$  the concentrations of the acid on the surface and in the bulk, and  $\beta$  the diffusion rate constant, the apparent dissolution rate is expressed by [9]:

$$\frac{1}{v_2} = \frac{[(v_1/\beta)c_1^m + c_1]^n}{c_1^m v_1} \quad (29)$$

Here  $n$  and  $m$  are the true and apparent orders of the reaction on the surface. The concentrations  $c$  and  $c_1$  are related by the expression

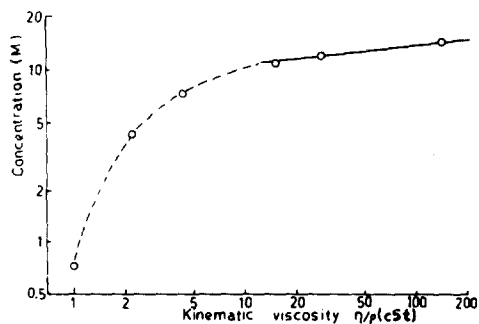


Figure 1 Graph showing the relationship between kinematic viscosity,  $\eta/\rho$  (cSt), and concentration  $c$  (M) of H<sub>3</sub>PO<sub>4</sub> [11].

$$c = \frac{v_1}{\beta} c_1^m + c_1 \quad (30)$$

The dependence of viscosity on concentration at high values of the latter is of the form  $c = k_1(\eta/\rho)^{n'}$  (Fig. 1) and  $\beta = \eta/\rho\delta_f$ , assuming that  $\delta_f = k_2 c^{n''}$ . Here  $k_1$ ,  $k_2$ ,  $n'$  and  $n''$  are constants and  $\eta$  and  $\rho$  the viscosity and density of the etchant. In terms of  $c$  and  $\eta/\rho$ , Equation 29, using Equation 30, may be written in the form

$$\begin{aligned} \log v_2 &= (1 - n - n'' - 1/n) \log c \\ &+ (1/n) \log k_1 + \log k_2 \\ \log v_2 &= (n' - n'n'' - 1) \log (\eta/\rho) \\ &+ (1 - n + n'') \log k_1 + \log k_2. \end{aligned} \quad (31)$$

#### 6. Comparison with experimental data

Equations 24 and 27 show that  $A_s$  and  $A_d$  grow with  $f$ ,  $\alpha$  and  $c$  and decrease with  $Z$  and  $r_f$ . Equations 25 and 28 show that the values of  $E_s$  and  $E_d$  depend on the energies of adsorption of H<sup>+</sup> and An<sup>-</sup> ions and of the complexes on the surface and at dislocations. Consequently, we can treat  $A$ 's and  $E$ 's separately.

##### 6.1. Pre-exponential factor

For the {100} face of MgO crystals,  $f = 1$ ,  $Z = 1$  and  $r_f = 1$ . Thus Equations 24 and 27 reduce to

$$\begin{aligned} A_s &= 3.66 \times 10^5 \phi \alpha c \\ A_d &= 2.0 \times 10^7 \phi \alpha c. \end{aligned} \quad (32)$$

The dependence of pre-exponential factors of dissolution for HCl, HNO<sub>3</sub>, H<sub>2</sub>SO<sub>4</sub>, H<sub>3</sub>PO<sub>4</sub> and HCOOH is similar (Fig. 2) following the relation

$$A = A_0(\alpha c^2)^{0.1} \quad (33)$$

where  $A$  denotes the pre-exponential factor for

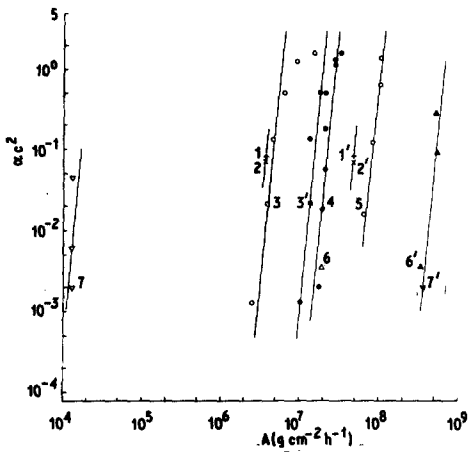


Figure 2 Plots of  $\alpha c^2$  versus pre-exponential factors  $A_s$  and  $A_d$  ( $\text{g cm}^{-2} \text{h}^{-1}$ ) of surface dissolution (curves 1 to 7) and selective etching along the surface (curves 1'–7'). 1 and 1',  $\text{HNO}_3$ ; 2 and 2',  $\text{HCl}$ ; 3 and 3',  $\text{H}_2\text{SO}_4$ ; 4,  $\text{H}_3\text{PO}_4$ ; 5 and 5',  $\text{HCOOH}$ ; 6 and 6',  $\text{CH}_3\text{COOH}$  and 7 and 7',  $\text{C}_2\text{H}_5\text{COOH}$ .

dissolution of the surface as well as at dislocation sites, and  $A_0$  a constant corresponding to the value of the pre-exponential factor at  $\log(\alpha c^2) = 1$ .  $A_0$  is related to the degree of dissociation,  $\alpha$ , of an acid (Fig. 3) by the equations

$$\begin{aligned} A_{0s} &= 3.0 \times 10^6 \alpha^{-1} \\ A_{0d} &= 1.0 \times 10^7 \alpha^{-1} \end{aligned} \quad (34)$$

for surface dissolution and selective etching, respectively. Thus

$$\begin{aligned} A_s &= 3.0 \times 10^6 \alpha^{-0.9} c^{0.2} \\ A_d &= 1.0 \times 10^7 \alpha^{-0.9} c^{0.2} \end{aligned} \quad (35)$$

Equations 32 and 35 are fairly well in agreement if

$$\phi = 1/(\alpha^{1.9} c^{0.8}) \quad (36)$$

According to the Freundlich isotherm [9], the surface coverage of the adsorbate

$$\theta = \frac{\alpha'}{m'} \exp(\Delta S_a m' T) \cdot c^{m' RT} \quad (37)$$

where  $\alpha'$  is the surface concentration of the occupied sites on the surface,  $m'$  is a constant and  $\Delta S_a$  the increase in the entropy of adsorption; obviously  $\phi = 1/\theta$ . Since the Freundlich isotherm is applicable for adsorption up to one monomolecular thickness and in our case  $m'RT = 0.8$ , it follows that the adsorption involved in the dissolution of  $\text{MgO}$  in dilute  $\text{HCl}$  and  $\text{HNO}_3$  and at all concentrations of  $\text{H}_2\text{SO}_4$ ,  $\text{H}_3\text{PO}_4$  and  $\text{HCOOH}$  is of less than monomolecular thickness.

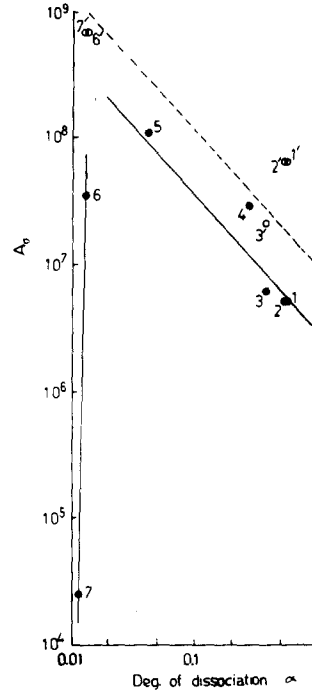


Figure 3 Dependence of  $A_0$  (see text) on degree of dissociation  $\alpha$ : 1 and 1',  $\text{HNO}_3$ ; 2 and 2',  $\text{HCl}$ ; 3 and 3',  $\text{H}_2\text{SO}_4$ ; 4,  $\text{H}_3\text{PO}_4$ ; 5 and 5',  $\text{HCOOH}$ ; 6 and 6',  $\text{CH}_3\text{COOH}$ ; 7 and 7',  $\text{C}_2\text{H}_5\text{COOH}$ . Points 1 to 7, lower curve, for surface dissolution and 1' to 7', upper curve, for selective etching.

In the case of dissolution in dilute  $\text{CH}_3\text{COOH}$  and  $\text{C}_2\text{H}_5\text{COOH}$

$$A_s = 7.0 \times 10^{101} \alpha^{50.1} c^{0.2}$$

Comparing this with Equation 32, one gets

$$\phi = 1.9 \times 10^{96} \alpha^{49.1} c^{-0.8} \quad (38)$$

whence

$$\theta = c^{0.8} / (1.9 \times 10^{96} \alpha^{49.1}) \quad (39)$$

This indicates that though here also  $m'RT = 0.8$ ,  $\theta$  is a complicated function of  $\alpha$  unlike in other acids.

## 6.2. Activation energy of dissolution

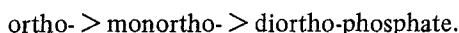
From Equations 25 and 28 it follows that knowing the values of  $[\frac{1}{4}(E_1 + E_2) + \frac{1}{2}E_3 + E_4]$ ,  $[\frac{1}{4}(E'_1 + E'_2) + \frac{1}{2}E'_3 + E'_4]$  and  $\Delta H^0$ ,  $E_s$  and  $E_d$  may be estimated. At somewhat higher  $\text{HCl}$  concentrations, the values of  $[\frac{1}{4}(E'_1 + E'_2) + \frac{1}{2}E'_3]$  and  $E'_4$  for  $\text{MgO}$  have been computed to be 0.17 eV and 0.15 eV [10]. Although  $[\frac{1}{4}(E_1 + E_2) + \frac{1}{2}E_3]$  may be taken to be equal to  $[\frac{1}{4}(E'_1 + E'_2) + \frac{1}{2}E'_3]$ ,  $E_4$  remains unknown. Therefore  $E_s$  cannot be

TABLE III Heat of formation and activation energies of surface dissolution and selective etching of MgO in some acid solutions

Acid	$\Delta H^0$ (kcal mol <sup>-1</sup> )	$E_d$ (eV)		$E_s$ (eV)
		Estimated	Observed	
HCl	34.90	1.07	0.68	0.59 0.55
HNO <sub>3</sub>	34.89	1.07	0.68	0.59
H <sub>2</sub> SO <sub>4</sub>	34.89	1.07	0.65	0.59
H <sub>3</sub> PO <sub>4</sub>	122.54	2.96	—	0.62

estimated. Substituting the typical values of  $[\frac{1}{4}(E'_1 + E'_2) + \frac{1}{2}E'_3]$  and  $E'_4$ , and the values of  $\Delta H^0$  from the literature [12], the calculated  $E_d$  for some acids is given in Table III. The experimentally observed values of  $E_d$  and  $E_s$  in dilute solutions of the acids are also listed in the table.

It may be noted that the observed  $E_d$  values for HCl, HNO<sub>3</sub> and H<sub>2</sub>SO<sub>4</sub> are about two-thirds of the calculated values. It also appears that the expected experimental  $E_d$  in the case of H<sub>3</sub>PO<sub>4</sub> should be far smaller than the calculated value. This disagreement indicates the formation of still heavier activated complexes. Further, the heat of formation of phosphates changes in the sequence:



Since in our calculations we have used the heat of formation of Mg<sub>3</sub>(PO<sub>4</sub>)<sub>2</sub> in place of Mg(H<sub>2</sub>PO<sub>4</sub>)<sub>2</sub>, the observed greater discrepancy is natural.

The values of activation energy of dissolution at low and high concentrations of some acids are observed [3] to be comparatively high. Since the heat of adsorption,  $[\frac{1}{4}(E_1 + E_2) + \frac{1}{2}E_3]$ , of H<sub>2</sub>O is higher than that of HCl and HNO<sub>3</sub>, a higher activation energy at low concentrations is expected (cf. Equations 25 and 28). The heat of adsorption at monomolecular thicknesses is larger than that involved in polymolecular adsorption [13], therefore the increased activation energy at very high acid concentrations could be due to the setting-in of only monolayer adsorption.

Since the change in the energy of physical adsorption on different faces is negligible, Equations 25 and 28 also indicate that the activation energy does not change appreciably from one surface to another. Experimental results on the selective etching of different faces of MgO corroborate this inference.

### 6.3. Energy of a dislocation and adsorption

From Equations 25 and 28

$$[\frac{1}{4}(E'_1 + E'_2) + \frac{1}{2}E'_3 - \frac{1}{4}(E_1 + E_2) - \frac{1}{2}E_3] - (E'_4 - E_4) = E_d - E_s.$$

Since for physical adsorption

$$[\frac{1}{4}(E'_1 + E'_2) + \frac{1}{2}E'_3] \simeq [\frac{1}{4}(E_1 + E_2) + \frac{1}{2}E_3]$$

the difference in the energies of dissolution may be attributed mainly to the difference in the energy of adsorption of the complex on the surface and at a dislocation site. Therefore

$$(E'_4 - E_4) = (E_d - E_s) = \frac{1}{p}E_c \quad (40)$$

where  $1/p$  is a proportionality constant which signifies the extent of adsorption at a dislocation site, and  $E_c$  dislocation energy. The experimentally obtained values of  $(E_d - E_s)$  and the corresponding  $1/p$  using  $E_c = 1.3$  eV [14] are given in Table IV.

The energy of adsorption of a complex non-polar molecule is the sum of the adsorption energy of the groups constituting it [13]. Therefore the energy of adsorption of the molecules of acetic, propionic and citric acids at dislocation sites may be supposed to be relatively high. Consequently, these acids produce good etch pits on the {100} face of MgO crystals [3, 15]. The significance of  $1/p$  is therefore clear: the higher the value of  $1/p$ , the better is the revelation of etch pits (Table IV).

### 6.4. Surface orientation effects

Assume that the adsorption factor  $\phi$  follows the same relationship, expressed by Equations 36 and 38 on different crystallographic planes. Then two cases arise, namely, when the effects of free bonds are either significant or insignificant. Using Equations 24 and 27 the expected anisotropy in the two cases may be obtained (Table V). Thus the pre-exponential factor changes in the sequence  $\{100\} > \{111\} > \{110\}$  and  $\{100\} > \{110\} > \{111\}$  in the cases when the effects of free bonds are insignificant and significant, respectively.

The observed relative rates of dissolution [4] in H<sub>2</sub>SO<sub>4</sub> and H<sub>3</sub>PO<sub>4</sub> are given in Table VI. From Tables V and VI, the effect of the number of free bonds on dissolution in 4N H<sub>2</sub>SO<sub>4</sub> and in 2.21 and 44.1 N H<sub>3</sub>PO<sub>4</sub> is obvious. In concentrated H<sub>2</sub>SO<sub>4</sub> the free bond effect is negligible.

TABLE IV Relationship between the estimated values of dislocation core energy  $E_c$ , ( $E_d - E_s$ ),  $1/p$  and pit formation at dislocation sites

Acid	Reference	$E_s$ (eV)	$E_d$ (eV)	$(E_d - E_s)$ (eV)	$1/p$	Remarks on pit dimensions at dislocations	Nature of etching
HCl	[3]	0.55	0.68	0.13	0.10	s <sup>†</sup>	Deep etch pits at fresh, shallow pits at old dislocations
	[2]	0.59	0.68	0.09	0.07	s + e	
HNO <sub>3</sub>	[2]	0.59	0.68	0.09	0.07	s + e	Deep etch pits at fresh, shallow pits at old dislocations
H <sub>2</sub> SO <sub>4</sub>	[2]	0.59	0.65	0.06	0.05	s + e	Deep etch pits at fresh, shallow pits at old dislocations
HCOOH	[3]	0.65	0.70	0.05	0.04	o	Shallow pits at old dislocations
CH <sub>3</sub> COOH	[3]	0.66	0.81	0.15	0.12	s	Deep pits at old and fresh dislocations
C <sub>2</sub> H <sub>5</sub> COOH	[3]	0.47	0.76	0.29	0.22	s	Deep pits at old and fresh dislocations

<sup>†</sup>s = screw, e = edge and o = old dislocations.

TABLE V Calculated relative pre-exponential factors of different faces

Face	{100}	{110}	{111}
$n_{Mg}$	$1.1322 \times 10^{15}$	$0.8006 \times 10^{15}$	$0.8716 \times 10^{15}$
$f$	1	1.3	1.15
Relative $A_s$ for $Z = 1$	1	1.8	1.5
Relative $A_s$ for $Z = 1, 2, 3$	1	0.9	0.5

TABLE VI Relative etch rates and pre-exponential factors of dissolution in some acids

Etchant	Temperature °C	{100}	{110}	{111}
Polishing				
4 N H <sub>2</sub> SO <sub>4</sub>	23	1	0.77	0.75
36 N H <sub>2</sub> SO <sub>4</sub>	23	1	1.38	1.38
2.21 N H <sub>3</sub> PO <sub>4</sub>	23	1	0.91	1.36
	65	1	0.68	0.68
44.1 N H <sub>3</sub> PO <sub>4</sub>	65	1	0.57	0.75
Selective etching				
4 N H <sub>2</sub> SO <sub>4</sub>	†	1	0.54	0.75
36 N H <sub>2</sub> SO <sub>4</sub>	†	1	1.54	2.46

<sup>†</sup>Ratio of pre-exponential factors of dissolution between 20 and 80° C.

### 6.5. Effect of acid concentration and viscosity on dissolution rate

Equation 31 shows that the dissolution rate of a diffusion-controlled process is independent of the reaction rate at the surface, and that it depends only on  $c$  and  $\eta/\rho$ . Since  $n < 1$  [1, 2] and  $n' < 1$  (Fig. 1), for a simple case when  $n'' = 1$ , we have

$$\log v_2 = -K_1 \log c + \log K_2$$

$$\log v_2 = -K'_1 \log (\eta/\rho) + \log K'_2 \quad (41)$$

where  $K$ 's are constants. This equation shows that dissolution rate decreases with an increase in  $c$  and  $\eta/\rho$ . Experiments [2, 4] bear out this inference.

The temperature dependence of  $\eta/\rho$  follows an



TABLE VII Etch pits and pyramids on {100} MgO surfaces and the corresponding concentrations, degree of dissociation and entropy of adsorption in different acids

Acid	Concentration (M)	Degree of dissociation $\alpha$	$\Delta S_a$ (kcal mol <sup>-1</sup> K <sup>-1</sup> )	Observed etching behaviour
HNO <sub>3</sub>	0.1	$5.66 \times 10^{-1}$	- 8.10	<110> pits
	8.0	$9.00 \times 10^{-2}$	- 11.60	<100> pits and also pyramids
HCl	0.1	$5.22 \times 10^{-1}$	- 8.26	<110> pits
	8.0	$6.70 \times 10^{-2}$	- 12.16	<100> pits and also pyramids
H <sub>2</sub> SO <sub>4</sub>	0.1	$3.58 \times 10^{-1}$	- 8.97	<110> pits
	4.5	$6.45 \times 10^{-2}$	- 12.23	<100> pits and pyramids
	9.0	$4.60 \times 10^{-2}$	- 12.87	<100> pits and pyramids
	18.0	$3.28 \times 10^{-2}$	- 13.51	<100> pits and hillocks
H <sub>3</sub> PO <sub>4</sub>	0.1	$2.81 \times 10^{-1}$	- 9.43	<100> pits
	3.0	$6.00 \times 10^{-2}$	- 12.37	<100> pits and pyramids
	13.2	$2.85 \times 10^{-2}$	- 13.78	pyramids
HCOOH	0.1	$4.11 \times 10^{-2}$	- 13.08	<100> pits
	3.0	$7.95 \times 10^{-3}$	- 16.21	pyramids
	22.0	$2.24 \times 10^{-3}$	- 18.6	pyramids
CH <sub>3</sub> COOH	0.1	$1.31 \times 10^{-2}$	-15.85	<100> pits and also pyramids
	9.0	$1.39 \times 10^{-3}$	94.29	<100> pits
C <sub>2</sub> H <sub>5</sub> COOH	0.1	$1.15 \times 10^{-2}$	- 9.46	<100> pits
	9.0	$1.22 \times 10^{-3}$	100.69	<100> pits

Arrhenius-type equation. Therefore if the plots of  $v_{s,a}$  versus  $1/T$  and of  $\eta/\rho$  versus  $1/T$  give identical values of activation energy, dissolution may be taken as diffusion-controlled.

From a study of overall (surface) dissolution of MgO in concentrated H<sub>2</sub>SO<sub>4</sub> the activation energy of dissolution was observed to be approximately equal to that of viscosity decrease, but that corresponding to selective etching was relatively high [4]. This indicates that though the dissolution process at the surface is diffusion-controlled, the local reactivity at dislocations may still render it partly or fully chemically-controlled. Hence while inferring the nature of rate-limiting kinetics from the dependence of selective etch rate on  $1/T$  one should be cautious.

### 6.6. Etch pits and pyramids

The etching behaviour [1–3, 16] of the acids used in our analysis is summarized in Table VII. Clearly etch pits are formed in many acid solutions, while etch pyramids are formed in concentrated HCl, HNO<sub>3</sub>, moderately concentrated H<sub>2</sub>SO<sub>4</sub> and in H<sub>3</sub>PO<sub>4</sub> and HCOOH in a wide concentration range.

Using Equations 36 and 37, we have

$$m'RT = 0.8 \quad (42)$$

$$\alpha^{1.9} = \frac{\alpha'}{m'} \exp(\Delta S_a m' T) \quad (43)$$

at  $T = 300$  K,  $m' = 1.33 \times 10^{-3}$ . Substituting the values of  $T$  and  $m'$ , and arbitrarily taking  $\alpha' = 1$ , Equation 43 reduces to

$$\alpha^{1.9} = 1.12 \times 10^3 e^{\Delta S_a} \quad (44)$$

Obviously  $\Delta S_a$  is a function of  $\alpha$ . Substituting the values of  $\alpha$  corresponding to the concentrations given in Table VII,  $\Delta S_a$  may be estimated (Table VII).

Similarly, using Equations 37 and 39, one obtains

$$\alpha^{-49.1} = 2.13 \times 10^{99} e^{\Delta S_a}. \quad (45)$$

Substituting the values of  $\alpha$  for CH<sub>3</sub>COOH and C<sub>2</sub>H<sub>5</sub>COOH, the  $\Delta S_a$  values here may also be obtained (Table VII).

Since we are dealing with adsorption where the heat of adsorption is always positive. Consequently,  $\Delta S_a$  should also be positive. This is contrary to our expectation. Even in a very dilute solution,  $\Delta S_a$  turns out to be negative. The reason

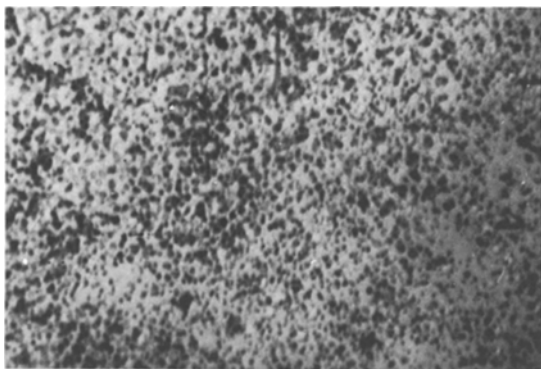


Figure 4 Etch pyramids formed by 0.87 N  $\text{CH}_3\text{COOH}$  at  $27.5^\circ\text{C}$  after  $5\frac{1}{2}$  h ( $\times 150$ ).

for this is associated with the assumption that  $\alpha' = 1$ . In an ideal acid solution where the degree of dissociation  $\alpha \approx 1$  it can be shown (cf. Equation 44) that for  $\Delta S_a = 0$ , the concentration of the occupied sites  $\alpha' \approx 0.1\%$ . For smaller values of  $\alpha$  which is usually the case,  $\alpha'$  should still be smaller in the case of acids other than  $\text{CH}_3\text{COOH}$  and  $\text{C}_2\text{H}_5\text{COOH}$ . Without investigating further this aspect of  $\alpha'$ , some interesting features of the etching process can, nevertheless, be noted on the basis of the trend of the change of entropy of adsorption alone.

With an increase in the concentration of  $\text{HNO}_3$ ,  $\text{HCl}$ ,  $\text{H}_2\text{SO}_4$ ,  $\text{H}_3\text{PO}_4$  and  $\text{HCOOH}$ , pyramids,  $\langle 100 \rangle$  pits, circular pits and  $\langle 110 \rangle$  pits are formed in that order. In  $\text{CH}_3\text{COOH}$  at very low concentrations ill-defined rounded  $\langle 100 \rangle$  pits are formed, but on prolonged etching pyramids are produced (Fig. 4). At high concentrations of  $\text{CH}_3\text{COOH}$  and in  $\text{C}_2\text{H}_5\text{COOH}$ ,  $\langle 100 \rangle$  pits are produced. Table VII shows these results in terms of the increase in entropy of adsorption. With increasing entropy of adsorption in an acid, pyramids,  $\langle 100 \rangle$  pits, circular pits and  $\langle 110 \rangle$  pits are formed in that order. A relatively large change in the adsorption entropy in the case of  $\text{CH}_3\text{COOH}$  and  $\text{C}_2\text{H}_5\text{COOH}$  in the same concentration range can also be the cause of the formation of contrasting etch pits in concentrated solutions of these acids.

## 7. Conclusions

(1) The application of activated complex theory in conjunction with the adsorption of reacting species and complexes on MgO surfaces provides a fairly satisfactory explanation of the dependence of dissolution rates at surface and at dislocation sites on the temperature, concentration and nature

of an acid and on the surface orientation of MgO crystals.

(2) The dissolution process is accompanied by physical adsorption of the reactants and the complexes (also activated complex). In dilute solutions of acids the adsorption corresponds to a layer of less than monomolecular thickness. The formation of pits and pyramids is associated with the adsorption process.

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